

MA27P120G

Silicon planar type

For high frequency switch

■ Features

- Small terminal capacitance C_t
- Low forward dynamic resistance r_f

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|----------------------|-----------|-------------|------------------|
| Reverse voltage | V_R | 60 | V |
| Forward current | I_F | 100 | mA |
| Power dissipation * | P_D | 150 | mW |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *: With a glass epoxy PC board.

■ Package

- Code
SSSMini2-F3
- Pin Name
1: Anode
2: Cathode

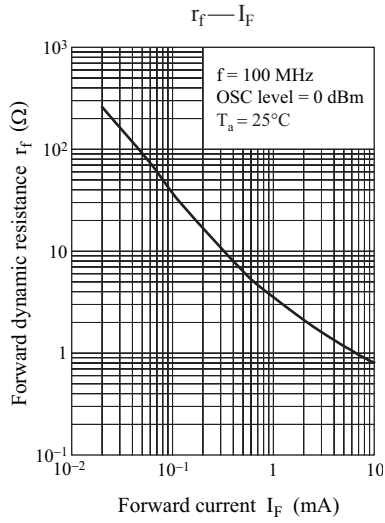
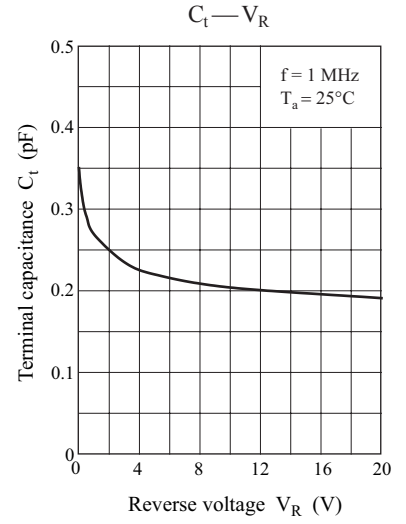
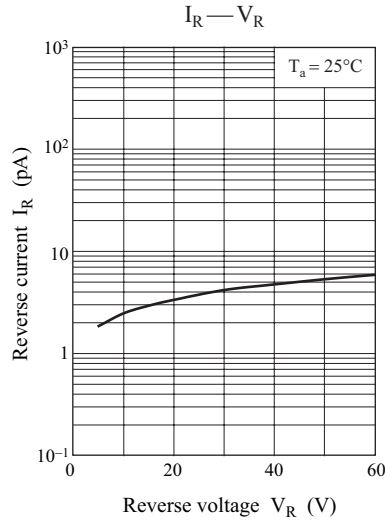
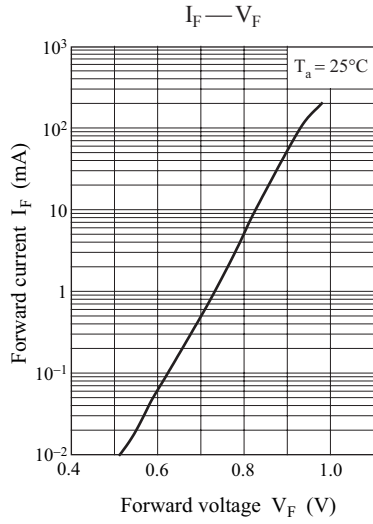
■ Marking Symbol: U

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|------------------------------|--------|--|-----|------|-----|----------|
| Forward current | V_F | $I_F = 10 \text{ mA}$ | | | 1.0 | V |
| Reverse current | I_R | $V_R = 60 \text{ V}$ | | | 100 | nA |
| Terminal capacitance | C_t | $V_R = 1 \text{ V}, f = 1 \text{ MHz}$ | | 0.27 | | pF |
| Forward dynamic resistance * | r_f | $I_F = 10 \text{ mA}, f = 100 \text{ MHz}$ | | 0.8 | | Ω |

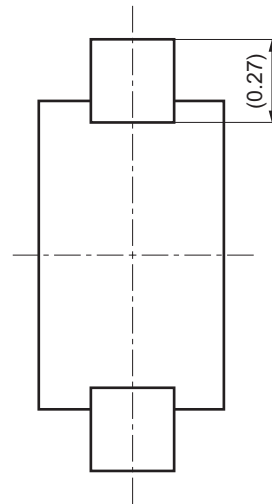
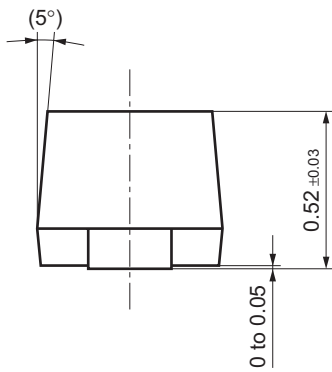
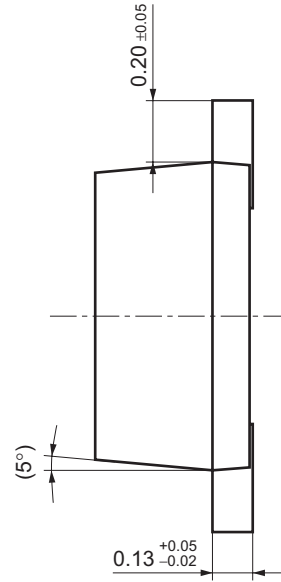
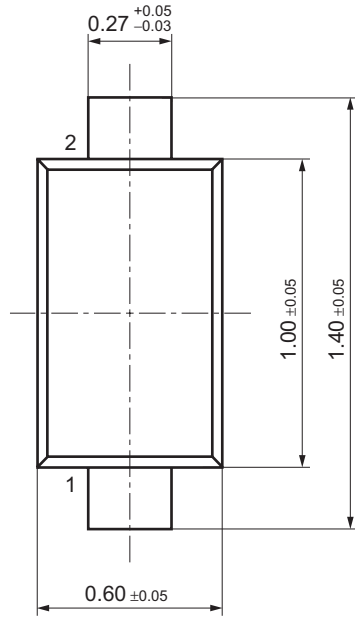
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. *: r_f measurement device: agilent model 4291B



SSSMini2-F3

Unit: mm



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